

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

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 APPLICANT
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 GROUP **1775**
Not yet assigned

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
LX	4,425,205	01/1984	Honma et al.			
LX	4,734,175	03/1988	Bissinger			
LX	5,730,356	03/1998	Omasa			
LX	6,120,673	09/2000	Reiter et al.			

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
LX	60-125379	July 4, 1985	JAPAN (with English abstract)				
LX	3-191070	Aug. 21, 1991	JAPAN (with English abstract)				
LX	4-325688	Nov. 16, 1992	JAPAN (with English abstract)				
LX	6-101056	Apr. 12, 1994	JAPAN (with English abstract)				
LX	6-264248	Sept. 20, 1994	JAPAN (with English abstract)				
LX	6-340979	Dec. 13, 1994	JAPAN (with English abstract)				

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

LX	"Electroless Copper Plating Using Co(II) Compound as Reducing Agent", S. Nakao et al., The Surface Finishing Society of Japan Summary Report of the 98th Conference, 19A-34, pp. 33-34
	"The Autocatalytic Deposition of Tin", M. E. Warwick et al., Transactions of the Institute of Metal Finishing, 1980, Vol. 58, pp. 9-14

EXAMINER

DATE CONSIDERED

10/22/03